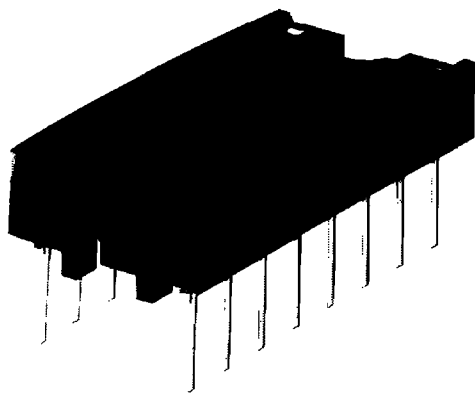


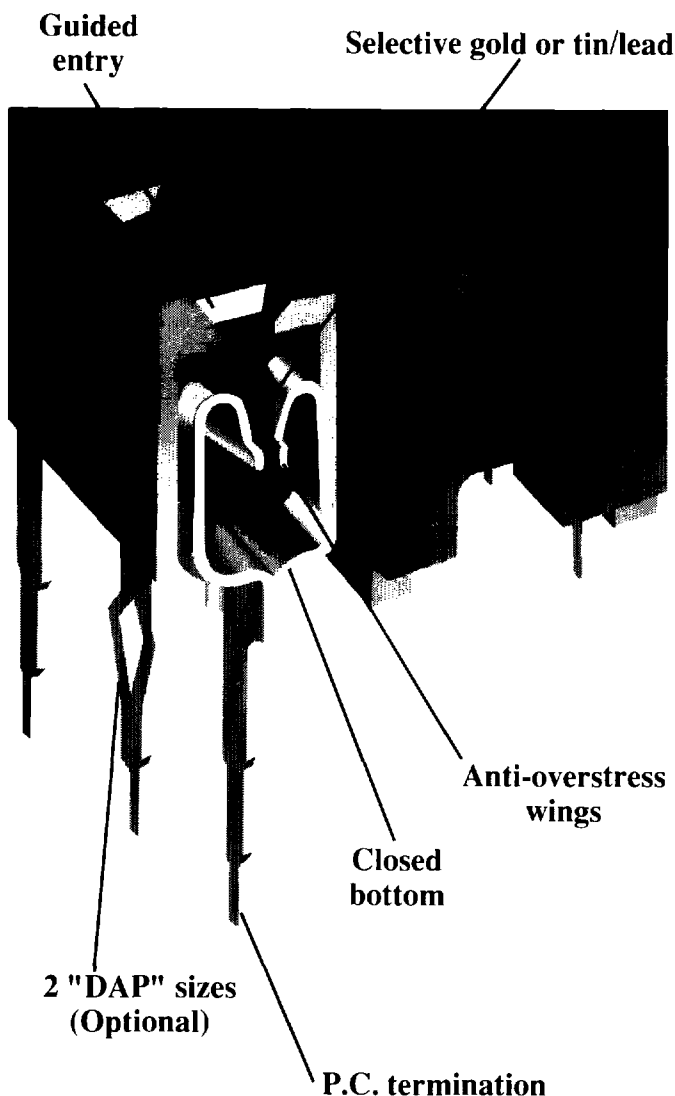
400C Series | Stamped Dual Beam DIP Sockets

NEW



The Augat 400C Series Dual Beam Contact Socket provides a new dimension in reliability, redundant electrical contacts and consistent mechanical performance in a low cost socket.

- Patented Stamped Dual Beam provides two fully independent electrical connections.
- "X" and "Y" stackable insulator for maximum package density.
- Protected open entry for easy IC insertion.
- Dual tapered lead for easy auto-insertability.
- Optional "DAP" feature on every fourth pin allows socket to be retained in PWB during automatic or hand insertion without clinching leads.
- Non-wicking, closed bottom contact design gives protection against flux and solder contamination.
-  recognized under the Component Program of Underwriters Laboratories, Inc. file no. E111362.



APPLICATION DIMENSIONS

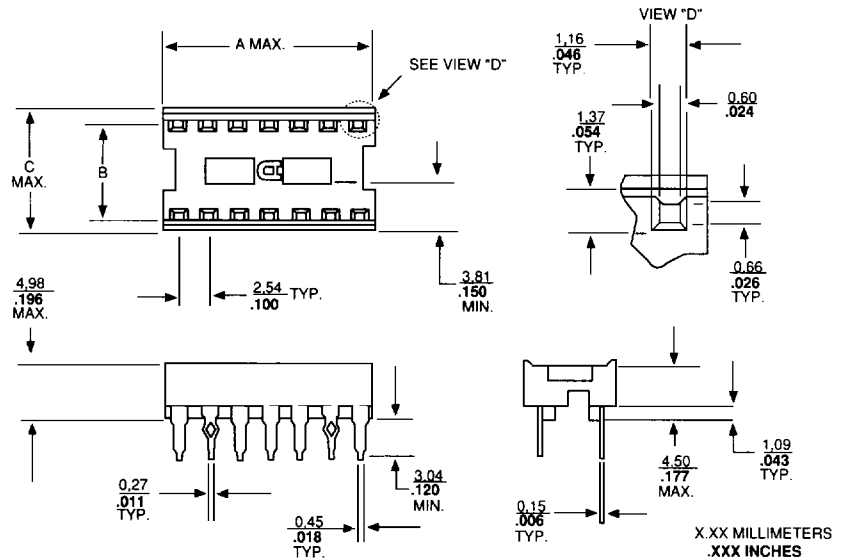
- PWB Thickness Range: Standard .062" and .092"
- PWB Hole Size Range: Standard Tail .035" $\pm$.003"
- IC Pin Dimension Range: .009" X .023" through .015" x .023", .100" Min. Length
- Insertion Force Per DAP: Phosphor Bronze 2.5 Lbs. Average, BeCu 3.8 Lbs. Average

400C Series

STANDARD CONFIGURATIONS

NO. OF CONTACTS	A	B $\pm .013$ $\pm .005$	C
8	10.16 .400	7.62 .300	10.16 .400
14	17.78 .700		
16	20.32 .800		
18	22.86 .900		
20	25.40 1.000		
24*	30.48 1.200		
22	27.94 1.100	10.16 .400	12.70 .500
24	30.48 1.200	15.24 .600	17.78 .700
28	35.56 1.400		
40	50.80 2.000		
48	60.96 2.400		
64	81.28 3.200		

DIMENSIONS mm/in



PART NUMBER EXAMPLE (416-AG218DC)

4	X	X	—A	G	X	X	D	C
400 SERIES	NUMBER OF CONTACTS (8-64) (See chart for stand- ard configurations)				X	TERMINATION D-PC		
					CONTACT MATERIAL AND PLATING 19—Phos. Bronze Tin/Lead 18—Phos. Bronze Selective Gold 10μ" 39—BeCu Tin/Lead 15—BeCu Selective Gold 10μ" 49—BeCu Selective Gold 30μ"			
"DAP" FEATURE (Plated thru hole) 1—.035" Dia. 2—.040" Dia. Omit for standard PC Tail					* Exception: 24 Contact .300" Centers 10—Phos. Bronze Tin/Lead 38—Phos. Bronze Selective Gold 10μ" 30—BeCu Tin/Lead 35—BeCu Selective Gold 10μ" 32—BeCu Selective Gold 30μ"			

MATERIAL SPECIFICATIONS

INSULATOR	Thermoplastic Polyester Rated 94V-0
CONTACTS	Phosphor Bronze CDA 521 (Per QQ-B-750) Beryllium Copper CDA 150 (Per QQ-C-533)
PLATING	90/10 Tin/Lead (Per MIL-P-81728) 10μ" or 30μ" Selective Gold over Nickel on Contact Surface (Per MIL-G-45204), 90/10 Tin/Lead on Solder Tail

PERFORMANCE CHARACTERISTICS

Stamped Dual Beam Contactpg. H6